



HSEC8-DV SERIES

(0.80 mm) .0315"

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DV

Insulator Material:

Black Liquid Crystal Polymer Contact:

Plating: Au or Sn over 50 μ" (1.27 μm) Ni Current Rating: 2.8 A per pin

2.6 A per pin (2 adjacent pins powered) Operating Temp: -55 °C to +125 °C RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (10-60)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Card Mates:

(1.60 mm) .062" card, (2.36 mm) .093" card, HSC8

Cable Mates:

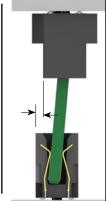


or (2.36 mm) .093" cards

Mates with (1.60 mm) .062"

MITIGATION

MISALIGNMENT



OTHER

OPTION

Custom designs compensate for misalignment.

HIGH-SPEED CHANNEL PERFORMANCE

VERTICAL EDGE RATE® CARD SOCKET

HSEC8-DV

Rating based on Samtec reference channel For full SI performance data visit Samtec.com or contact SIG@samtec.com

HSEC8



09, 10, 13, 20,

25, 30, 37, 40, 49,

50, 60, 70, 80, 100

(13, 25, 49 only available with –L or –L2 option; 09 only available with –L2 option;

37 only available with -L option)

No. of Positions x (0.80) .0315 + (7.80) .307

CARD

THICKNESS

-01 (1.60 mm) .062"

> thick card -03

(2.36 mm) .093 thick card

PLATING OPTION

= 10 µ" (0.25 µm)

Gold on contact Matte Tin on tail

= 30 µ" (0.76 µm) Gold on contact, Matte Tin on tail

(7.00)

(1.75) .070

- **–K** (7.01 mm) .276" DIA Polyimide Film Pick & Place Pad; with –01 card,
- (6.25 mm) .246" DIA Polyimide Film Pick & Place Pad; with -03 card

-BL

= Board Locks -01 card only (Weld tab standard)

= Latching Option; -01 card only (13, 25, 37, 49 only) (Weld tab standard)

-L2

= ECDP Latching; -01 card only (09, 13, 25, 49 only) (For use with ECDP) (Weld tab standard)

-WT = Weld tab

–TR

= Tape & Reel (09 - 70 only)

= Full Reel Tape & Reel Packaging (Must order max. quantities per reel Contact Samtec for parts per reel) (09 - 70 only)

CABLE CONNECTOR ECDP-04 HSEC8-109-L2 ECDP-08 HSEC8-113-L2 ECDP-16 HSEC8-125-L2 ECDP-32 | HSEC8-149-L2

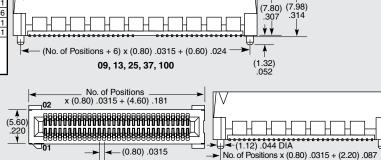
POSITIONS PER ROW	Α	В
09*†	(4.50) .177	(11.80) .465
13*†	(6.10) .240	(15.00) .591
25*†	(6.10) .240	(24.60) .969
37†	(18.10) .713	(34.20) 1.346
40	(18.90) .744	(36.60) 1.441
49*†	(22.90) .902	(43.80) 1.724
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071
70†	(26.90) 1.059	(60.60) 2.386
80†	(26.90) 1.059	(68.60) 2.701
100t	(26.90) 1.059	(84.60) 3.331

Positions where no dimensions are given do not have keving feature.

Mates with ECDP Series † Available with -01 Card Only

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

Some lengths, styles and options are non-standard, non-returnable.



10, 20 & 30 Due to technical progress, all designs, specifications and components are subject to change without notice I WWW.SAMTEC.COM I

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